


Fig. 1A

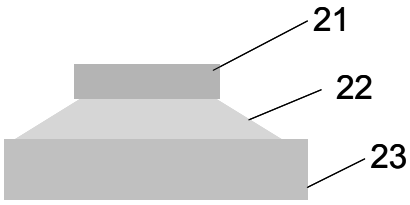



Fig. 1B

PRIOR ART

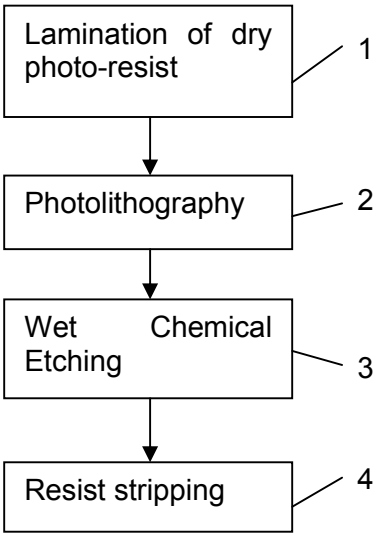

Lamination of dry photo-resist
1
Photolithography
2
Wet Chemical Etching
3
Resist stripping
4

Fig. 2

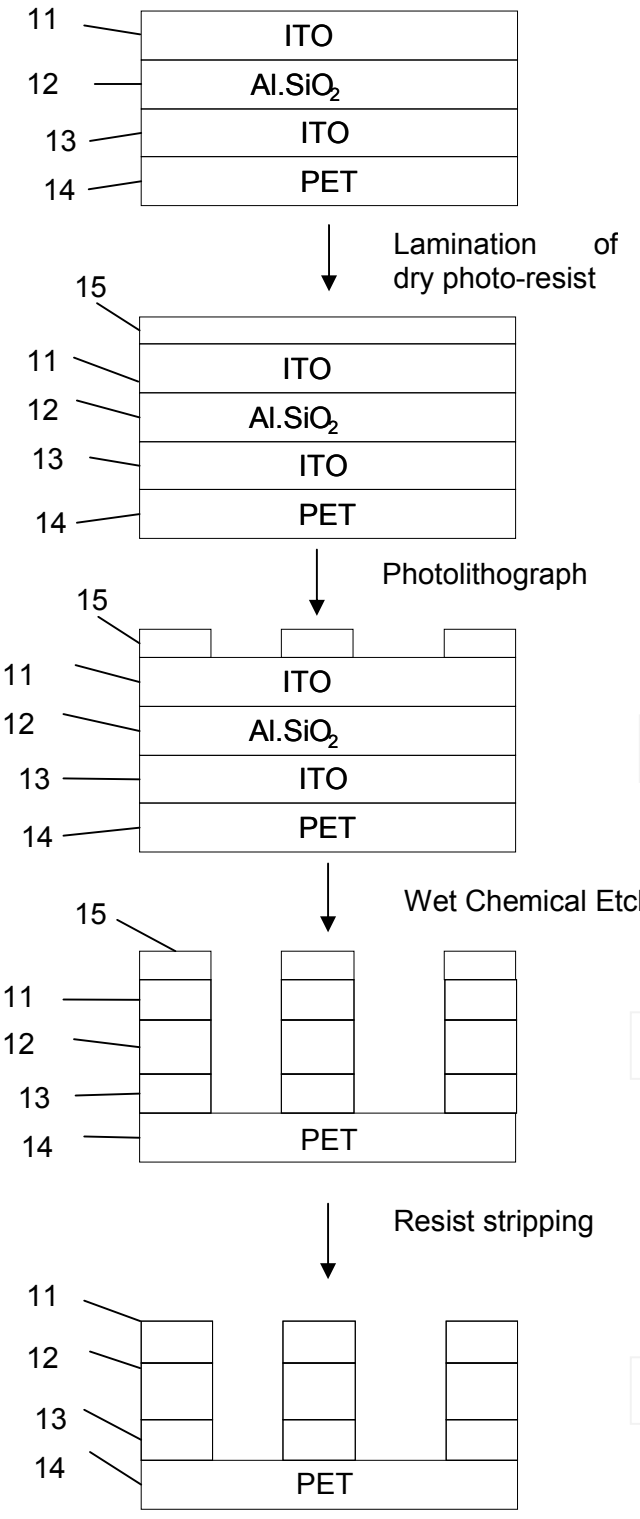



Fig. 3A

Fig. 3B

Fig. 3C

Fig. 3D

Fig. 3E

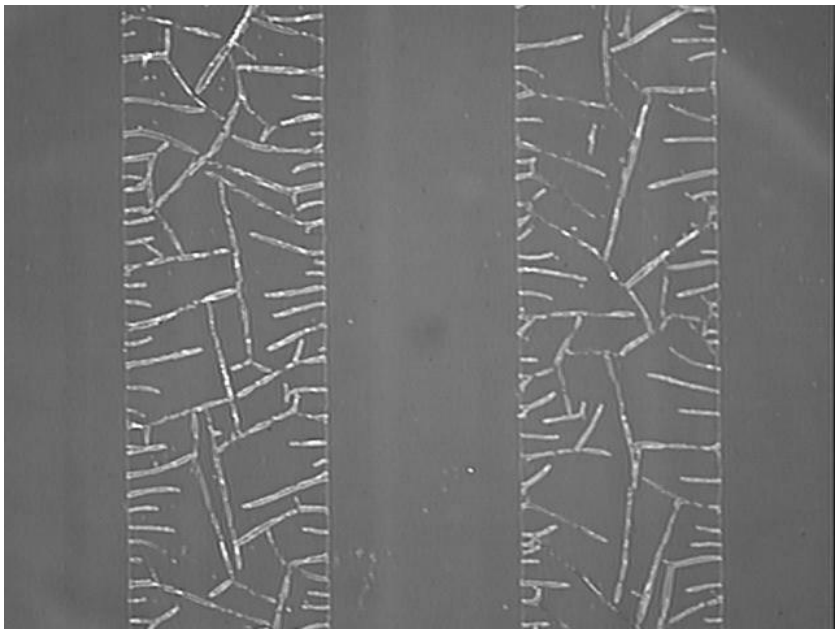


FIG. 4

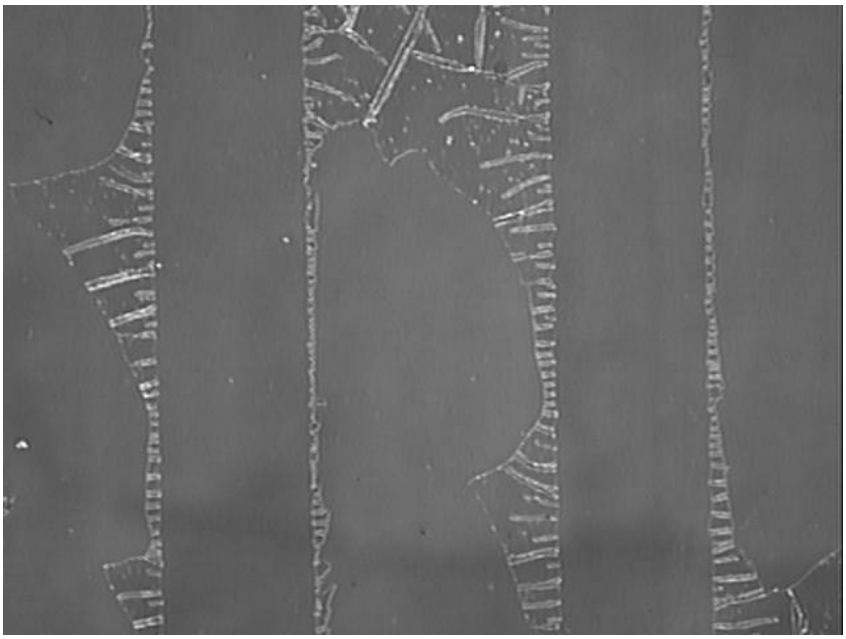


FIG. 5

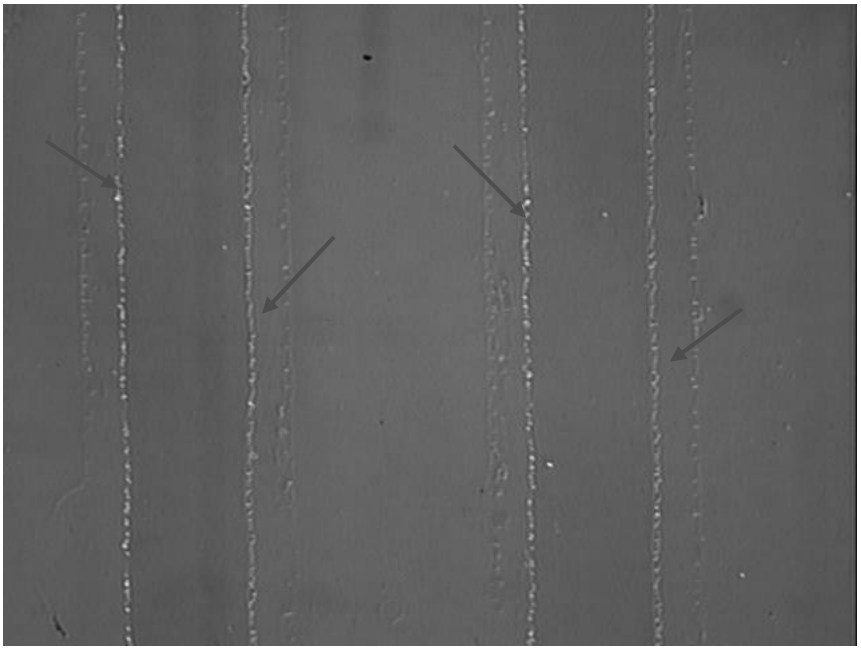


FIG. 6

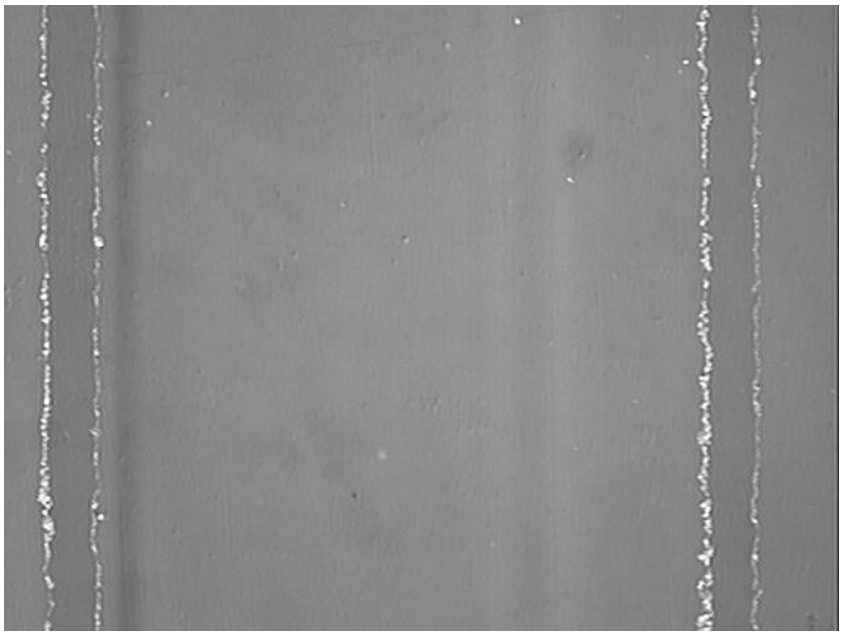


FIG. 7

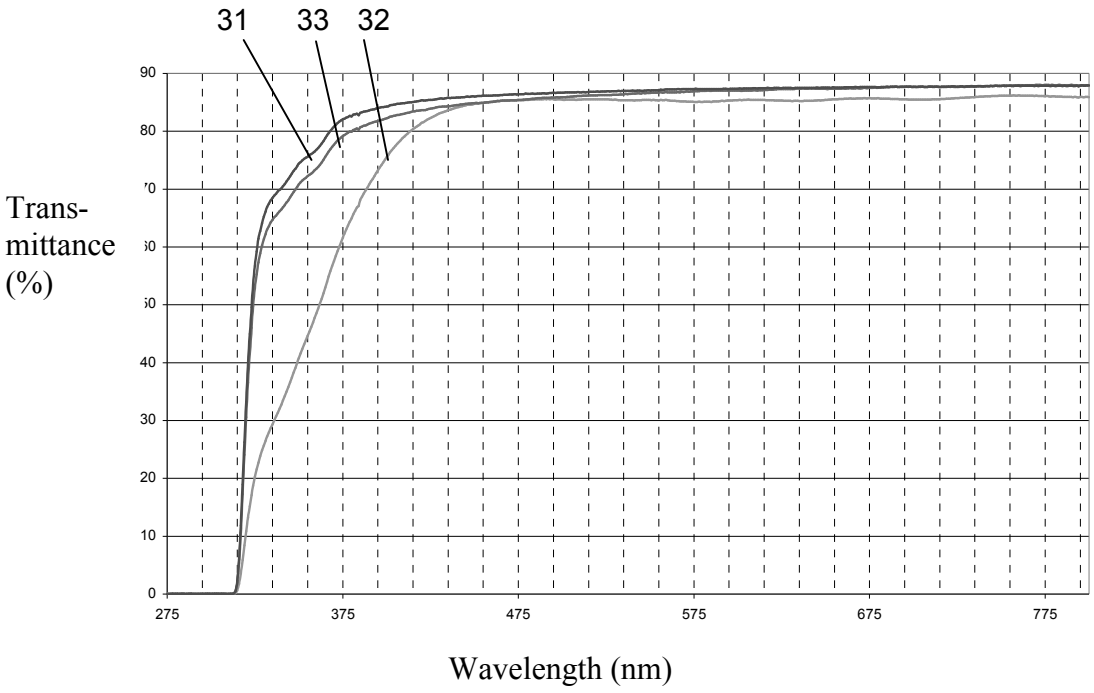

31
33
32
Trans-
mittance
(%)
90
80
70
60
50
40
30
20
10
0
275
375
475
575
675
775
Wavelength (nm)

FIG. 8

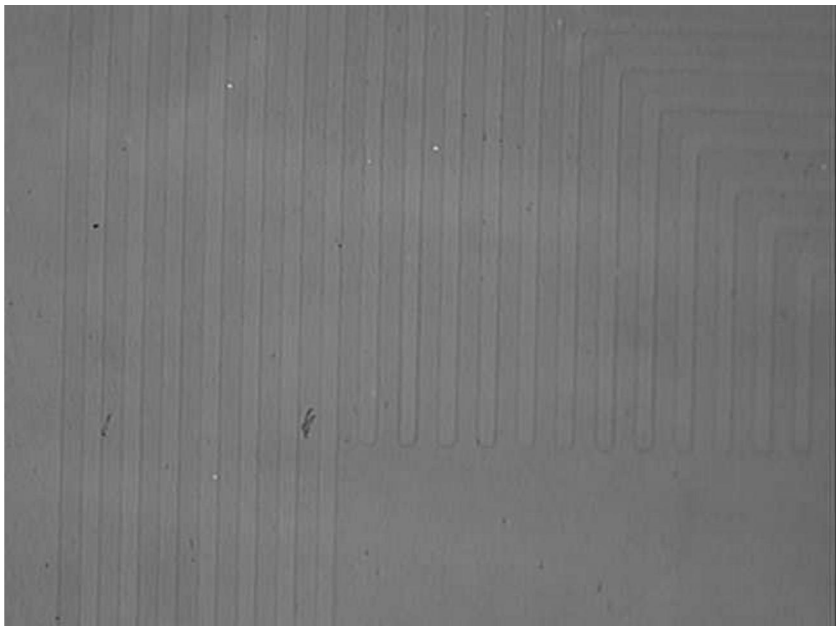


FIG. 9A



FIG. 9B

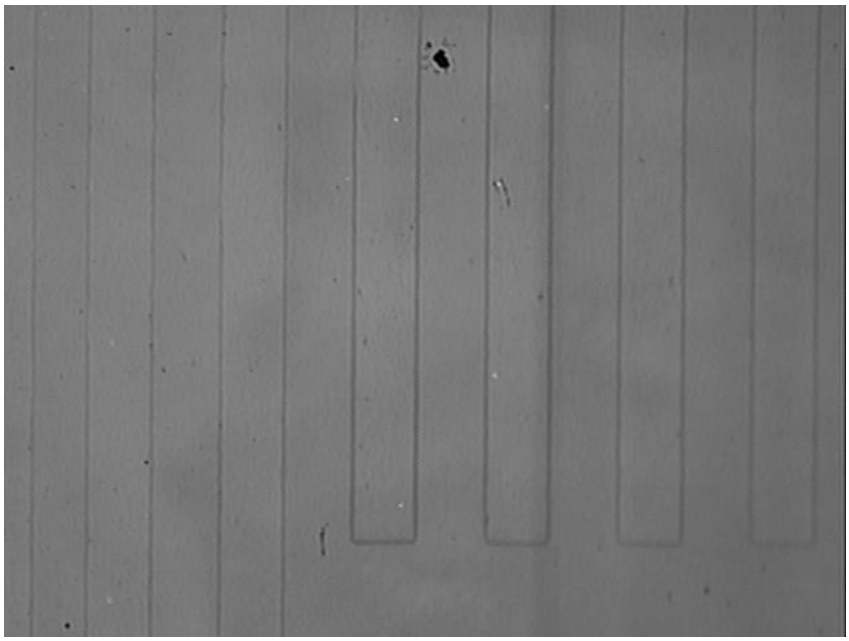


FIG. 9C

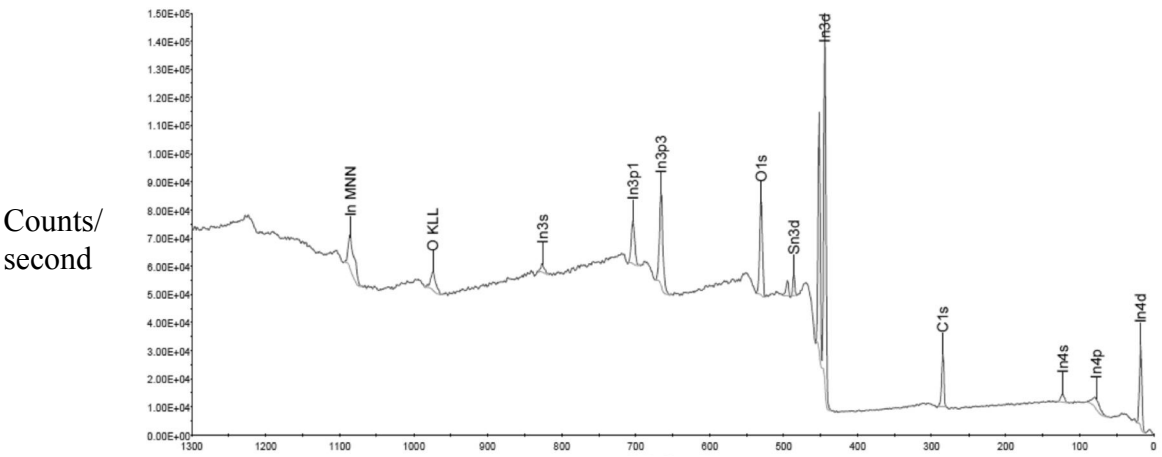



FIG. 10A

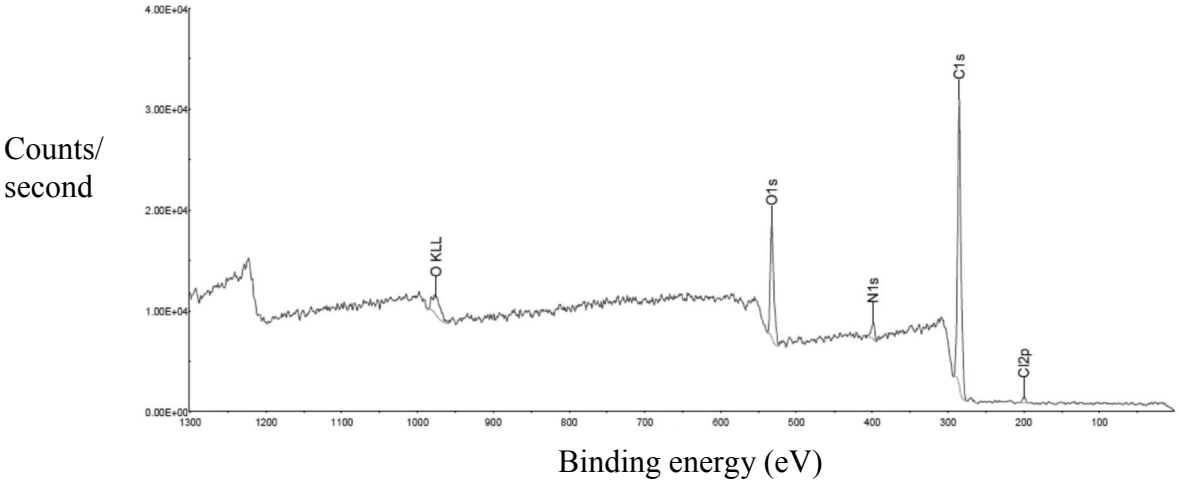



FIG. 10B

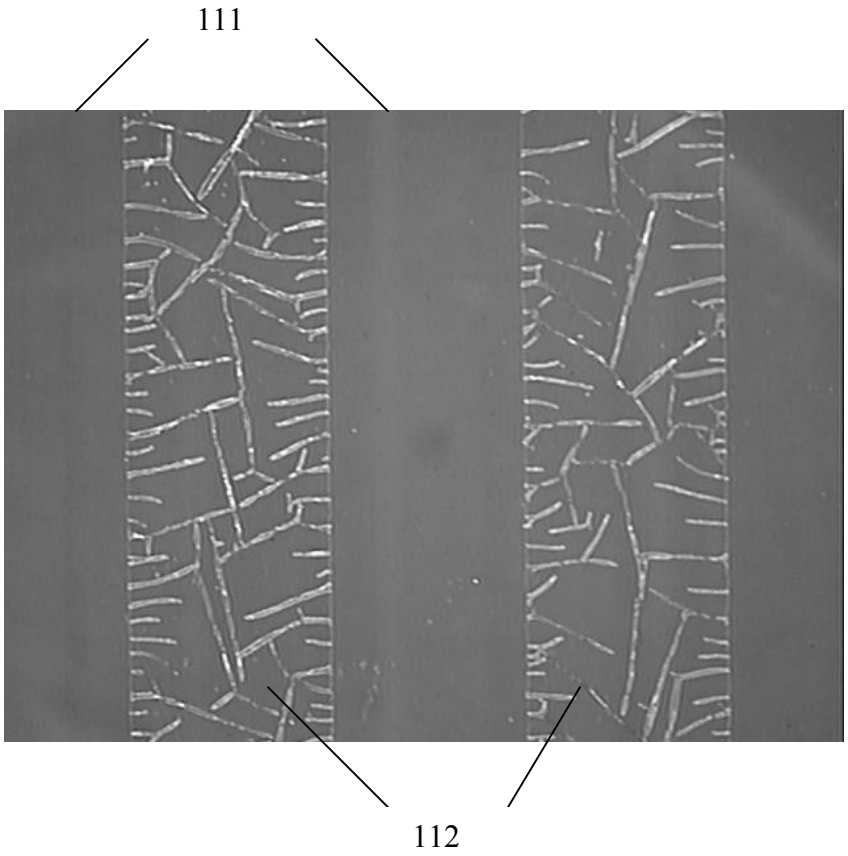



FIG. 11A

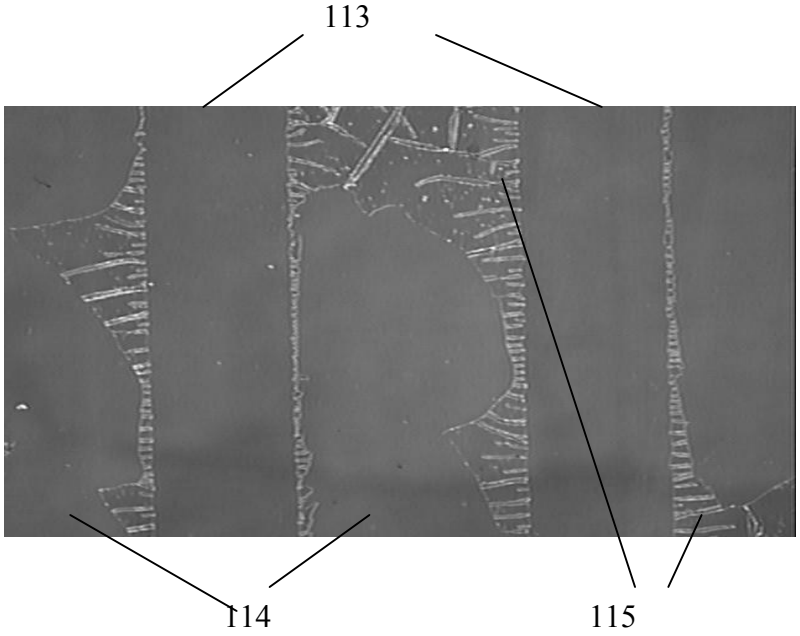



FIG. 11B

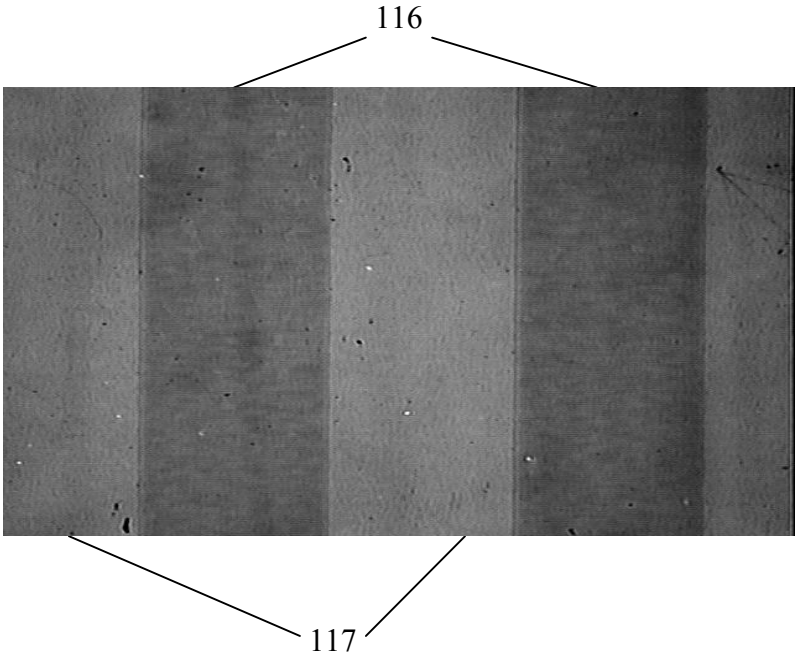



FIG. 11C

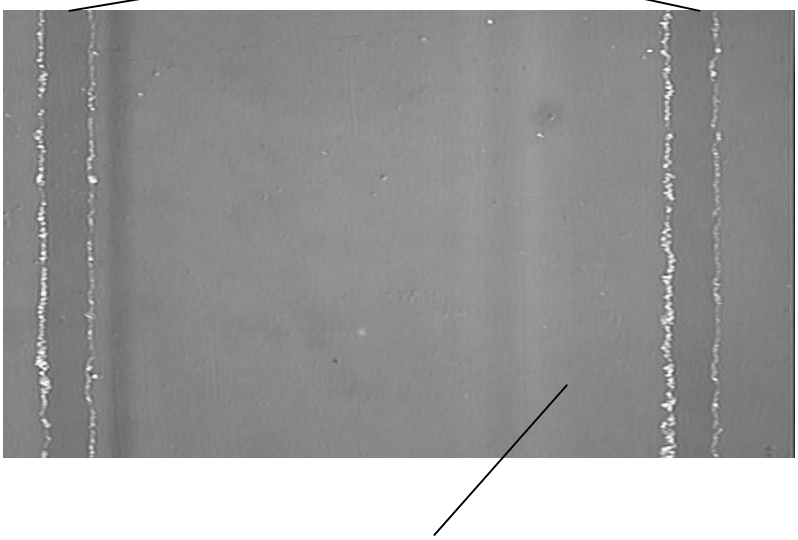



FIG. 11D

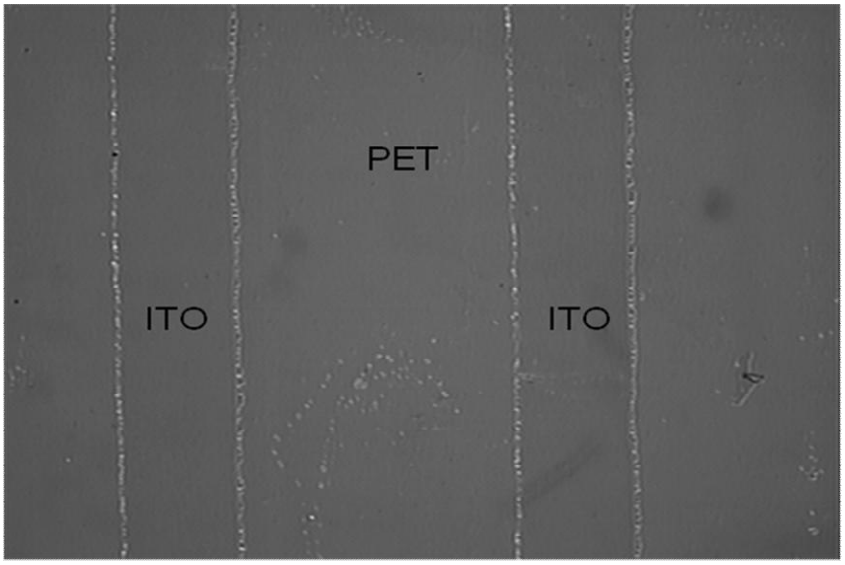



FIG. 12